

**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q79041

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Group Art Unit: 2823

Confirmation No.: 1863

Examiner: Khiem D. NGUYEN

Filed: January 29, 2004

For: SOLDER DISPOSITION METHOD AND SOLDER BUMP FORMING METHOD

**AMENDMENT UNDER 37 C.F.R. § 1.111**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

This Amendment is submitted in response to the Office Action dated October 18, 2007.

Review and reconsideration on the merits in view of the following remarks and amendments is respectfully requested.

A Petition for Extension of Time for one month is attached hereto and incorporated herein by reference, extending the time for response from January 18, 2008 to February 18, 2008.

A Statement of Substance of Interview is submitted herewith.

Please amend the above-identified application as follows on the accompanying pages.

**TABLE OF CONTENTS**

AMENDMENTS TO THE CLAIMS.....	2
REMARKS .....	9